dielectric	COG/NPO CG/ N	X7R / B	X7S / K
temperature	-55℃125℃	-55℃125℃	-55℃125℃
coefficient	±30ppm/°C	±15%	±22%

## **Use precautions**

Please be sure to attach the purchase specification before using this product.

## Safety precautions

When using this product, please pay attention to safety matters.

## **Application restrictions**

Before using our products, please contact us with the following applications that require high reliability in particular to prevent defects that may directly cause damage to the life, body or property of a third party.

- Underwater equipment (1) Aircraft equipment (2) Aerospace equipment
- (6) Transportation equipment (vehicles, trains, ships, etc.) (5) Medical equipment

(8) disaster prevention/crime prevention equipment

(D) Complexity and/or reliability requirements similar to those of the above applications.

## **Transportation and storage methods**

## 1. Transport

The packaging products are suitable for modern transportation, and should be protected from rain and acid and alkali corrosion during transportation. They shall not be thrown by gravity or squeezed violently.

2. Storage (Refer to IEC 61760-2, Clause 6 Storage conditions/IEC 60721-3-1: 2018, class 1K21)

The storage period of the product with good weldability is: two years from the date of production. Do not open the tape before using the product (in the case of well packed and delivered), and the product should be used within three months after opening the tape.

Storage temperature: 5°C~40°C Storage temperature: 5°C~40°C

Storage relative humidity: 10%~75% Storage relative humidity: 10%~75%

Environment: Harmless chemical environment Environment: Harmless chemical environment

Packaging: original packaging of core sound Packaging: original packaging of core sound

Solar radiation: 700 W/m<sup>2</sup>, direct light should be avoided Solar radiation: 700 W/m<sup>2</sup>, direct light should be avoided

## Characteristic

- ≻ Complies with AEC-Q200 standard
- ≻ Complies with MSL 1 standard
- $\triangleright$ Complies with J-STD-020D standard
- High reliability and equipment reliability
- ≻ Passed 100% six-sided appearance inspection test

## Application

- Car audio and video
- Body electronics
- High reliability
- Industrial applications

No.	name
1	dielectric
2	Internal electrode (nickel)
3	External electrodes (copper)
4	nickel layer
5	The tin layer



Structure diagram





- ⑦ Traffic signal equipment
- ③ Data processing equipment







## Part number example

<b>CCAH</b>	<u>0603</u>	B	<u>104</u>	<u>K</u>	<u>1H</u>	<u>G</u>	<u>T</u>
(1)	(2)	(3)	(4)	(5)	(6)	(7)	(8)

No.			size code			
(1) Application		urpose for automobile			•	
		ode		nch		system (mm)
		R4		004		201
		R5 201		005		402 503
	-	402	-	.02		05
(2)	-	503		03		508
size		305		05	20	012
		206		.06		216
		210		10		225
		308 312	-	12	-	520 532
		220		20		750
(3) temperature characteristic	Class I : C0G Class II : X7R X7	~				
(4) Capacitance value	First 2×10^3 104=10×10^4=10 123=12×10^3=12			0=1pF		
(5)	A : ±0.05pF	B : ±0.1pF	C: ±0.25pF	D:±0.5pF	F:±1.0%	G: ±2%
Capacitance tolerance	J:±5%	K:±10%	M: ±20%			
	0E:2.5	0G:4.0	0J:6.3	1A:10	2C:16	2E:25
(6)	1V:35	1H:50	1J:63	2A:100	2D:200	2E:250
Rated voltage (Vdc)	2W:450	2H:500	2J:630	3A:1000	3D:2000	3E:2500
(140)	3U:3000	3G:4000				
(7)	A: 0.10	B: 0.13	C:0.18	D: 0.20	E: 0.30	F: 0.45
Product thickness	G: 0.50	Н: 0.60	J: 0.80	K: 0.85	L:1.15	M: 1.25
(mm)	N: 1.60	P:1.90	Q:2.00	S: 2.30	R: 2.50	
(8) Packaging method	T: Finished packag	ging (7"Reel)				

In general,  $\varphi$ 180mm (7") trays are used for packaging.

## **Size & packing specifications** Five discs are packaged in one box and twelve boxes are a whole box.



		size (	(mm)		Packagin	ng (7")
specifications	Length	Width	Thickness	g	Packaging quantity (pieces)	manner of packing
01R5	0.40±0.02	$0.20 \pm 0.02$	$0.20 \pm 0.02$	0.13	20,000	paper tape
0201	0.60±0.03 0.60+0.10/-0.03	0.30±0.03 0.30+0.10/-0.03	0.30±0.03 0.30+0.10/-0.03	0.20	15,000	paper tape
	1.00±0.05	0.50±0.05	0.50±0.05			
0.402	1.00±0.07	0.50±0.07	0.50±0.07	0.20	10,000	
0402	1.00±0.10	0.50±0.10	0.50±0.10	0.30	10,000	paper tape
	1.00+0.20/-0.05	0.50+0.20/-0.05	0.50+0.20/-0.05			
0603	1.60±0.10	$0.80 \pm 0.10$	$0.80 \pm 0.10$	0.60	4,000	manan tana
0005	1.60±0.20	$0.80 \pm 0.20$	$0.80 \pm 0.20$	0.00	4,000	paper tape
		size	(mm)		Packagin	
specifications	Length	Width	Thickness	g	Packaging quantity (pieces)	manner of packing
	$2.00 \pm 0.10$	$1.25 \pm 0.10$	$0.60 \pm 0.10$		4,000	paper tape
0805	2.00±0.10	1.25±0.10	$0.85 \pm 0.10$	0.70	4,000	puper upe
	2.00±0.20	$1.25 \pm 0.20$	$1.25 \pm 0.20$		3,000/2,000	Plastic strips
			$0.85 \pm 0.10$		4,000	paper tape
1206	3.20±0.20	$1.60 \pm 0.20$	$1.25 \pm 0.20$	1.50	3,000/2,000	Plastic strips
1206			$1.60 \pm 0.20$	1.50	2,000	Plastic strips
	3.20±0.30	1.60±0.30	$1.60 \pm 0.30$		2,000	Plastic strips
			0.85±0.10		2,000	Plastic strips
			$1.25 \pm 0.20$		2,000	Plastic strips
1210	$3.20 \pm 0.30$	$2.50 \pm 0.20$	$1.60 \pm 0.20$	1.50	2,000	Plastic strips
			2.00±0.20		2,000/1,000	Plastic strips
	3.20±0.40	2.50±0.30	2.50±0.30		2,000/1,000	Plastic strips
			1.25±0.20		2,000	Plastic strips
1808	4.50±0.40	$2.00 \pm 0.30$	1.60±0.20		2,000	Plastic strips
			2.00±0.20		1,000	Plastic strips
	4.50 + 0.20	2 2 4 0 20	1.25±0.20		1,000	Plastic strips
1012	$4.50 \pm 0.30$	$3.2 \pm 0.30$	$1.60 \pm 0.20$	0.50	1,000	Plastic strips
1812			2.00±0.20	2.50	1,000	Plastic strips
	$4.50 \pm 0.40$	$3.2 \pm 0.40$	2.50±0.30		500/1,000	Plastic strips
			$1.25 \pm 0.2$		1,000	Plastic strips
0000	5 50 . 0 . 0	5.0.1.0.10	1.60±0.20	2.50	700	Plastic strips
2220	$5.70 \pm 0.40$	$5.0 \pm 0.40$	2.00±0.20	3.50	700	Plastic strips
			2.50±0.3		700	Plastic strips

\* Please refer to the specification of a single particle for details

Tel: 0086-21-31263693

## Capacitance range 【C0G】 0402~0805

Size	thickness											COG	ŕ														
(inch)	(Code)	RV	R20	R30	1R0	2R2	4R7	100	150	220	330	470	680	101	151	221	331	471	681	102	152	222	332	472	682	103	333
0402	0.50	25																									
0402	(G)	50																									
	0.80	25																									
0603		50																									
	(J)	100																									
	0.60	25																									
0905	(H)	50																									
0805	1.25	25																									
	(M)	50																									
1206	1.60(N)	630																									
1210	2.50	500																									
1210	(R)	630																									

## 【X7R/X7S】 0201~1210

Size	thickness	RV									X7R/X	7S/X71	Γ							
(inch)	(Code)		151	221	471	102	152	222	472	103	223	473	104	224	474	105	225	475	106	226
	0.30	16																		
0201	(E)	25																		
		6.3														X7S				
		10														X7S				
0402	0.50(G)	16																		
0402	0.50(0)	25																		
		50																		
		100																		
		6.3															I		X7T	
		10																		
0603	0.80	16																		
	(J)	25																		
		50																		
		100																		
		16 25																		
	0.85	25 50																		
	(K)	100																		
		250																		
0805		6.3																		
	1.25	10																		
	(M)	16																	X7S	
	、 <i>,</i>	25																X7S	X7S	

Size	Thick	RV								2	X7R/X	7S/X71	Г							
(inch)	(Code)	(Vdc)	151	221	471	102	152	222	472	103	223	473	104	224	474	105	225	475	106	226
	1.25	50																X7S		
0805	(M)	100														X7S				
	(111)	250			-															
	0.85	50																		
	1.25	100																		
	(M)	500																		
	(101)	630																		
1206		10																		
1200		16																		X7S
	1.60	25																		
	(N)	50																	X7S	
		100															X7S			
		250																		
	2.00	50																		
	(Q)	100			-															
1210	2.50	16																		
	(R)	25																		
	(11)	50			-															
2220	2.30(S)	100																	X7S	

## Specifications and test methods

$\frac{1}{2} = \frac{1}{2} + \frac{1}$		•	<b>m</b> • • •		h			1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	
1       ess Electrical Test	No		Test specific	cations	Test method (I	Refe	erence sta	ndard: AEC-Q200-Re	v E)
2     High Temperature Exposure(Storage)     CoG: ±2.5% or ±0.25pF (whichever is greater)     Test temperature     150+/-3°C       2     High Temperature Exposure(Storage)     CoG: ±2.5% or ±0.25pF (whichever is greater)     Test temperature     150+/-3°C       2     Q or D.F.     Same as the initial specification value     testing time     1000 +/-12 hours       1.R.     Same as the initial specification value     testing time     1000 +/-12 hours       2     Capacitanc capacitanc     CoG: ±2.5% or ±0.25pF (whichever is greater)     method of greater)     Weld the capacitor to the test substrate       3     Temperature Cycling     CoG: ±2.5% or ±0.25pF (whichever is greater)     pretreatment x7R/X7S : ±10%     Heat treatment for 1 hour at 150+/-0/-10°C, then leave at room temperature for 24+/-2 hours before measurement       3     Temperature Cycling     Q or D.F.     Same as initial specification value     period:     15 minutes       4     (DPA)     surface     No defects or anomalies     temperature cycle     Istep temperature for 24+/-2 hours, temperature +0/-3     15+/-32       4     (DPA)     surface     No defects or anomalies     No defects or anomalies     Leave at room temperature for 24+/-2 hours, temperature +0/-3     15+/-32       5     Moisture Resistance     Surface     No defects or anomalies     No defects or anomalies     No defects or anomalies       5	1	ess Electrical							
2     High Temperature Exposure(Storage)     Capacitanc e changes     greater) X7R/X7S : ±10%     Iest emperature     150+/-3°C       2     High Temperature Exposure(Storage)     Q or D.F.     Same as the initial specification value     testing time     1000 +/-12 hours       1     Lave at room temperature for 24 +/-2 hours, then measure     Leave at room temperature for 24 +/-2 hours, then measure       3     Temperature Cycling     COG: ±2.5% or ±0.25pF (whichever is greater)     method of erection     Heat treatment for 1 hour at 150+/-0/-10°C, then leave at room temperature for 24+/-2 hours before measurement       3     Temperature Cycling     Q or D.F.     Same as initial specification value     period:     15 minutes       4     (DPA)     surface     No defects or anomalies     memperature cycle     Image: surface     No defects or anomalies       5     Moisture Resistance     surface     No defects or anomalies     No defects or anomalies     No defects or anomalies       5     Moisture Resistance     Surface     No defects or anomalies     Fest temperature +25°C     temperature +25°C			surface	No defects or anomalies.		We	ld the cap	pacitor to the test subst	rate
Image: Solution of the second seco		Exposure(Storage)	Capacitanc e changes	greater) X7R/X7S : ±10%		150	0+/-3°C		
3       Temperature Cycling       No defects or anomalies       method of erection       Weld the capacitor to the test substrate         3       Temperature Cycling       COG: ±2.5% or ±0.25pF (whichever is greater)       pretreatment       Heat treatment for 1 hour at 150+/-0/-10°C, then leave at room temperature for 24+/-2 hours before measurement         3       Temperature Cycling       Q or D.F.       Same as initial specification value       period:       15 minutes         4       DPA)       surface       No defects or anomalies       No defects or anomalies       No defects or anomalies         4       DPA)       surface       No defects or anomalies       No defects or anomalies       No defects or anomalies         5       Moisture Resistance       Surface       No defects or anomalies       Test temperature +25°C       to +65°C         5       Moisture Resistance       COG: ±3% or ±0.3pF (whichever is greater)       Test temperature +25°C to +65°C       Test temperature +25°C to +65°C			Q or D.F.	Same as the initial specification value	testing time	100	00 +/-12 h	ours	
$3 \begin{array}{ c c c c c c } \hline & & & & & & & & & & & & & & & & & & &$			I.R.	Same as the initial specification value	reprocessing			-	⊦/-2 hours,
$3 \operatorname{Temperature}_{Cycling} 4 \operatorname{(DPA)} \operatorname{surface}_{Resistance} \operatorname{No} \operatorname{defects} \operatorname{or} \operatorname{anomalies} \operatorname{surface}_{Capacitanc}_{e changes} \operatorname{capacitanc}_{greater} \operatorname{Surface}_{Condension} \operatorname{surface}_{Co$			surface	No defects or anomalies			Weld the	capacitor to the test su	bstrate
3       Temperature Cycling       Image: Same as initial specification value			Capacitanc e changes	greater)	pretreatment	t	then leave	e at room temperature	
3       Cycling       I.R.       Same as initial specification value       temperature cycle       1       Minimum operating temperature +0/-3       15+/-32         2       room temperature +0/-3       15+/-32       2       room temperature +0/-3       15+/-32         4       (DPA)       surface       No defects or anomalies       No defects or anomalies       No defects or anomalies         5       Moisture Resistance       Surface       No defects or anomalies       Test temperature +25°C to +65°C         6       CoG: ±3% or ±0.3pF (whichever is changes       Test temperature +25°C to +65°C       Test temperature +25°C to +65°C			Q or D.F.	Same as initial specification value	period:		15 minute	es	
I.R.       Same as initial specification value       Importative cycle       <	3	-			temperature		-	Minimum operating	Time (minutes) 15+/-32
I.R.       Same as initial specification value       Image: Same as initial specifi							2		1
4       (DPA)       surface       No defects or anomalies       No defects or anomalies         5       Moisture Resistance       Capacitance       COG: ±3% or ±0.3pF (whichever is changes       Test temperature       +25°C to +65°C         6       Cogratiance       Cograter)       Test temperature       +25°C to +65°C			I.R.	Same as initial specification value	cycle			Maximum operating	15+/-3
4       (DPA)       surface       No defects or anomalies       No defects or anomalies         4       (DPA)       surface       No defects or anomalies       method of erection         5       Moisture Resistance       Capacitanc echanges       COG: ±3% or ±0.3pF (whichever is greater)       Test temperature       +25°C to +65°C								1	1
5     Moisture Resistance     surface     No defects or anomalies     method of erection     Weld the capacitor to the test substrate       5     Moisture Resistance     COG: ±3% or ±0.3pF (whichever is greater)     Test temperature Test temperature     +25°C to +65°C					reprocessing				24 +/-2 hours
5 Moisture Resistance $Capacitance e changes$ $COG: \pm 3\% \text{ or } \pm 0.3 \text{pF} \text{ (whichever is greater)}$ $COG: \pm 3\% \text{ or } \pm 0.3 \text{pF} \text{ (whichever is greater)}$ $COG: \pm 3\% \text{ or } \pm 0.3 \text{pF} \text{ (whichever is greater)}$ $COG: \pm 3\% \text{ or } \pm 0.3 \text{pF} \text{ (whichever is greater)}$ $COG: \pm 3\% \text{ or } \pm 0.3 \text{pF} \text{ (whichever is greater)}$ $COG: \pm 3\% \text{ or } \pm 0.3 \text{pF} \text{ (whichever is greater)}$ $COG: \pm 3\% \text{ or } \pm 0.3 \text{pF} \text{ (whichever is greater)}$ $COG: \pm 3\% \text{ or } \pm 0.3 \text{pF} \text{ (whichever is greater)}$ $COG: \pm 2\% \text{ or } \pm 0.3 \text{pF} \text{ (whichever is greater)}$ $COG: \pm 2\% \text{ or } \pm 0.3 \text{pF} \text{ (whichever is greater)}$ $COG: \pm 2\% \text{ or } \pm 0.3 \text{pF} \text{ (whichever is greater)}$ $COG: \pm 2\% \text{ or } \pm 0.3 \text{pF} \text{ (whichever is greater)}$ $COG: \pm 2\% \text{ or } \pm 0.3 \text{pF} \text{ (whichever is greater)}$ $COG: \pm 2\% \text{ or } \pm 0.3 \text{pF} \text{ (whichever is greater)}$ $COG: \pm 2\% \text{ or } \pm 0.3 \text{pF} \text{ (whichever is greater)}$ $COG: \pm 2\% \text{ or } \pm 0.3 \text{pF} \text{ (whichever is greater)}$ $COG: \pm 2\% \text{ or } \pm 0.3 \text{pF} \text{ (whichever is greater)}$ $COG: \pm 2\% \text{ or } \pm 0.3 \text{pF} \text{ (whichever is greater)}$ $COG: \pm 2\% \text{ or } \pm 0.3 \text{pF} \text{ (whichever is greater)}$ $COG: \pm 2\% \text{ or } \pm 0.3 \text{pF} \text{ (whichever is greater)}$ $COG: \pm 2\% \text{ or } \pm 0.3 \text{pF} \text{ (whichever is greater)}$ $COG: \pm 2\% \text{ or } \pm 0.3 \text{pF} \text{ (whichever is greater)}$ $COG: \pm 2\% \text{ or } \pm 0.3 \text{pF} \text{ (whichever is greater)}$ $COG: \pm 2\% \text{ or } \pm 0.3 \text{pF} \text{ (whichever is greater)}$ $COG: \pm 2\% \text{ or } \pm 0.3 \text{pF} \text{ (whichever is greater)}$ $COG: \pm 2\% \text{ or } \pm 0.3 \text{pF} \text{ (whichever is greater)}$ $COG: \pm 2\% \text{ or } \pm 0.3 \text{pF} \text{ (whichever is greater)}$ $COG: \pm 2\% \text{ or } \pm 0.3 \text{pF} \text{ (whichever is greater)}$ $COG: \pm 2\% \text{ or } \pm 0.3 \text{pF} \text{ (whichever is greater)}$ $COG: \pm 2\% \text{ or } \pm 0.3 \text{pF} \text{ (whichever is greater)}$ $COG: \pm 2\% \text{ or } \pm 0.3 \text{pF} \text{ (whichever is greater)}$ $COG: \pm 2\% \text{ or } \pm 0.3 \text{pF} \text{ (whichever is greater)}$ $COG: \pm 2\% \text{ or } \pm 0.3 \text{pF} \text{ (whichever is greater)}$ $COG: \pm 2\% \text{ or } \pm 0.3 \text{pF}  (whichever is grea$	4	(DPA)	surface	No defects or anomalies	No defects or	anoi	malies		
5 Resistance changes greater) Test humidity 80% to 98% P H			surface	No defects or anomalies			Weld the	capacitor to the test su	bstrate
Resistance greater) e changes greater)	5	Moisture	Consistence	COG: $\pm 3\%$ or $\pm 0.3$ pF (whichever is	Test temperatu	ire	+25°C to	+65°C	
	5		e changes	X7R/X7S : ±15%					
Q or D.F. Same as initial specification value testing time Test 10 times for 24 hours (see figure below)			Q or D.F.	Same as initial specification value	testing time	Γ.	Test 10 tin	mes for 24 hours (see t	figure below)

No	item	Test specifi	cations	Test method (Ref	erence standard: AEC-Q200-Rev E)
5	Moisture Resistance	I.R.	Same as initial specification value	Temperature and humidity cycles	The formation of the fo
					Leave at room temperature for 24 +/-2 hours before measuring
		surface	No defects or anomalies	method of erection	Weld the capacitor to the test substrate
			COG: $\pm 2\%$ or $\pm 1$ pF (the larger value is	Test temperature	85+/-3℃
				Test humidity	80% to 85% R.H.
ſ		Q or D.F.	Please refer to the specification sheet for a single particle	testing time	1000 +/-12 hours
6	Biased Humidity		Please refer to the specification sheet for a	test voltage	Connect 100K $\Omega$ resistor and apply 150% R.V. Rated voltage (not exceeding 630V)
			single particle	Charging/dischar ge current	Maximum 50mA
				reprocessing	Leave at room temperature for 24 +/-2 hours, then measure
		surface	No defects or anomalies	method of erection	Weld the capacitor to the test substrate
		Capacitanc	COG: $\pm 2\%$ or $\pm 1$ pF (whichever is greater)	Test temperature	Maximum operating temperature +/-3°C
		e changes	X7R/X7S: ±15%	testing time	1000+/-12h
7	Operational Life	Q or D.F.	Please refer to the specification sheet for a single particle	test voltage	Please refer to the specification sheet for a single particle
			Please refer to the specification sheet for a	8	Maximum 50mA
		1.1.	single particle	reprocessing.	Leave at room temperature for 24 +/-2 hours, then measure
			or anomalies	Visual (microsco	
0					
9		In terms of		Use a size measur	ring instrument
10	Resistance to	surface Capacitanc	No defects or anomalies Same as the initial specification value		
10	Resistance to	surface Capacitanc e changes	No defects or anomalies Same as the initial specification value Same as the initial specification value		L-STD-202 Method 215
10	Resistance to	surface Capacitanc e changes	No defects or anomalies Same as the initial specification value		
10	Resistance to Solvents	surface Capacitanc e changes Q or D.F. I.R. surface	No defects or anomalies Same as the initial specification value Same as the initial specification value Same as the initial specification value	According to MII	
10	Resistance to Solvents	surface Capacitanc e changes Q or D.F. I.R. surface Capacitanc e changes	No defects or anomalies Same as the initial specification value Same as the initial specification value Same as the initial specification value No defects or anomalies Same as the initial specification value	According to MII method of erection wave form	STD-202 Method 215 Weld the capacitor to the test substrate Half sine
10	Resistance to Solvents	surface Capacitanc e changes Q or D.F. I.R. surface Capacitanc e changes	No defects or anomalies Same as the initial specification value Same as the initial specification value Same as the initial specification value No defects or anomalies	According to MII method of erection wave form peak value	L-STD-202 Method 215 Weld the capacitor to the test substrate Half sine 1500g
10	Resistance to Solvents	surface Capacitanc e changes Q or D.F. I.R. surface Capacitanc e changes	No defects or anomalies Same as the initial specification value Same as the initial specification value Same as the initial specification value No defects or anomalies Same as the initial specification value	According to MII method of erection wave form peak value holding time	2-STD-202 Method 215 Weld the capacitor to the test substrate Half sine 1500g 0.5ms
10	Resistance to Solvents Mechanical Shock	surface Capacitanc e changes Q or D.F. I.R. surface Capacitanc e changes Q or D.F.	No defects or anomalies Same as the initial specification value Same as the initial specification value Same as the initial specification value No defects or anomalies Same as the initial specification value Same as the initial specification value	According to MII method of erection wave form peak value holding time velocity change Direction and time of impact	Weld the capacitor to the test substrate Half sine 1500g 0.5ms 4.7m/s Each direction should be impacted three times (18 impacts) along the three mutually
10	Resistance to Solvents Mechanical Shock	surface Capacitanc e changes Q or D.F. I.R. surface Capacitanc e changes Q or D.F. I.R.	No defects or anomalies Same as the initial specification value Same as the initial specification value Same as the initial specification value No defects or anomalies Same as the initial specification value Same as the initial specification value	According to MII method of erection wave form peak value holding time velocity change Direction and time of impact method of	2-STD-202 Method 215 Weld the capacitor to the test substrate Half sine 1500g 0.5ms 4.7m/s Each direction should be impacted three
10	Resistance to Solvents Mechanical Shock	surface Capacitanc e changes Q or D.F. I.R. surface Capacitanc e changes Q or D.F. I.R. I.R. surface Capacitanc e changes	No defects or anomalies Same as the initial specification value Same as the initial specification value Same as the initial specification value No defects or anomalies Same as the initial specification value Same as the initial specification value Same as the initial specification value No defects or anomalies Same as the initial specification value	According to MII method of erection wave form peak value holding time velocity change Direction and time of impact method of erection	STD-202 Method 215 Weld the capacitor to the test substrate Half sine 1500g 0.5ms 4.7m/s Each direction should be impacted three times (18 impacts) along the three mutually perpendicular axes of the specimen
10	Resistance to Solvents Mechanical Shock Mechanical	surface Capacitanc e changes Q or D.F. I.R. surface Capacitanc e changes Q or D.F. I.R. I.R. surface Capacitanc e changes	No defects or anomalies Same as the initial specification value Same as the initial specification value Same as the initial specification value No defects or anomalies Same as the initial specification value Same as the initial specification value Same as the initial specification value	According to MII method of erection wave form peak value holding time velocity change Direction and time of impact method of erection Vibration type Vibration time	2-STD-202 Method 215 Weld the capacitor to the test substrate Half sine 1500g 0.5ms 4.7m/s Each direction should be impacted three times (18 impacts) along the three mutually perpendicular axes of the specimen Weld the capacitor to the test substrate A 10Hz~2000Hz~10Hz 20 minutes
10	Resistance to Solvents Mechanical Shock Mechanical Vibration	surface Capacitanc e changes Q or D.F. I.R. surface Capacitanc e changes Q or D.F. I.R. surface Capacitanc e changes Q or D.F.	No defects or anomalies Same as the initial specification value Same as the initial specification value Same as the initial specification value No defects or anomalies Same as the initial specification value Same as the initial specification value No defects or anomalies Same as the initial specification value	According to MII method of erection wave form peak value holding time velocity change Direction and time of impact method of erection Vibration type Vibration time total amplitude Direction and	X-STD-202 Method 215 Weld the capacitor to the test substrate Half sine 1500g 0.5ms 4.7m/s Each direction should be impacted three times (18 impacts) along the three mutually perpendicular axes of the specimen Weld the capacitor to the test substrate A 10Hz~2000Hz~10Hz 20 minutes 1.5mm Do 12 items (36 times in total) for every 3
10	Resistance to Solvents Mechanical Shock Mechanical Vibration	surface Capacitanc e changes Q or D.F. I.R. surface Capacitanc e changes Q or D.F. I.R. Surface Capacitanc e changes Q or D.F. I.R.	No defects or anomalies Same as the initial specification value Same as the initial specification value Same as the initial specification value No defects or anomalies Same as the initial specification value Same as the initial specification value Same as the initial specification value No defects or anomalies Same as the initial specification value Same as the initial specification value	According to MII method of erection wave form peak value holding time velocity change Direction and time of impact method of erection Vibration type Vibration type Vibration time total amplitude Direction and time of vibration	X-STD-202 Method 215 Weld the capacitor to the test substrate Half sine 1500g 0.5ms 4.7m/s Each direction should be impacted three times (18 impacts) along the three mutually perpendicular axes of the specimen Weld the capacitor to the test substrate A 10Hz~2000Hz~10Hz 20 minutes 1.5mm Do 12 items (36 times in total) for every 3 mutually perpendicular directions
10	Resistance to Solvents Mechanical Shock Mechanical Vibration	surface Capacitanc e changes Q or D.F. I.R. surface Capacitanc e changes Q or D.F. I.R. surface Capacitanc e changes Q or D.F. I.R.	No defects or anomalies Same as the initial specification value Same as the initial specification value Same as the initial specification value No defects or anomalies Same as the initial specification value Same as the initial specification value Same as the initial specification value No defects or anomalies Same as the initial specification value No defects or anomalies Same as the initial specification value Same as the initial specification value No defects or anomalies Same as the initial specification value No defects or anomalies	According to MII method of erection wave form peak value holding time velocity change Direction and time of impact method of erection Vibration type Vibration time total amplitude Direction and time of vibration test method	X-STD-202 Method 215 Weld the capacitor to the test substrate Half sine 1500g 0.5ms 4.7m/s Each direction should be impacted three times (18 impacts) along the three mutually perpendicular axes of the specimen Weld the capacitor to the test substrate A 10Hz~2000Hz~10Hz 20 minutes 1.5mm Do 12 items (36 times in total) for every 3 mutually perpendicular directions Solder bath method
10	Resistance to Solvents Mechanical Shock Mechanical Vibration	surface Capacitanc e changes Q or D.F. I.R. surface Capacitanc e changes Q or D.F. I.R. surface Capacitanc e changes Q or D.F. I.R. surface Capacitanc e changes Q or D.F.	No defects or anomalies Same as the initial specification value Same as the initial specification value Same as the initial specification value No defects or anomalies Same as the initial specification value Same as the initial specification value Same as the initial specification value No defects or anomalies Same as the initial specification value No defects or anomalies Same as the initial specification value Same as the initial specification value No defects or anomalies Same as the initial specification value No defects or anomalies	According to MII method of erection wave form peak value holding time velocity change Direction and time of impact method of erection Vibration type Vibration time total amplitude Direction and time of vibration test method	STD-202 Method 215      Weld the capacitor to the test substrate      Half sine     1500g     0.5ms     4.7m/s     Each direction should be impacted three     times (18 impacts) along the three mutually     perpendicular axes of the specimen     Weld the capacitor to the test substrate     A 10Hz~2000Hz~10Hz     20 minutes     1.5mm     Do 12 items (36 times in total) for every 3     mutually perpendicular directions     Solder bath method     Sn-3.0Ag-0.5Cu ( Lead Free Solder )
10	Resistance to Solvents Mechanical Shock Mechanical Vibration	surface Capacitanc e changes Q or D.F. I.R. surface Capacitanc e changes Q or D.F. I.R. surface Capacitanc e changes Q or D.F. I.R. surface Capacitanc e changes Q or D.F.	No defects or anomalies Same as the initial specification value Same as the initial specification value Same as the initial specification value No defects or anomalies Same as the initial specification value Same as the initial specification value Same as the initial specification value No defects or anomalies Same as the initial specification value Same as the initial specification value	According to MII method of erection wave form peak value holding time velocity change Direction and time of impact method of erection Vibration type Vibration time total amplitude Direction and time of vibration test method Welding material type	STD-202 Method 215      Weld the capacitor to the test substrate      Half sine     1500g     0.5ms     4.7m/s     Each direction should be impacted three times (18 impacts) along the three mutually perpendicular axes of the specimen      Weld the capacitor to the test substrate      A 10Hz~2000Hz~10Hz     20 minutes     1.5mm     Do 12 items (36 times in total) for every 3     mutually perpendicular directions     Solder bath method      Sn-3.0Ag-0.5Cu ( Lead Free Solder )

No	item	Test specific	cations	Test method (Ref	erence standard: AEC-Q200-Rev E)
14	Electrical static	surface	No defects or anomalies	According to AE	C-Q200-002
	testing (ESD)	Canacitano		- Fi	NU PASS
		e changes	Same as initial specification value	Z KV DC FAIL PASS	12 EV AD FAB. PASS
		Q or D.F.	Same as initial specification value		
		I.R.	Same as the initial specification value	voltage level t testing. Passive	Image from a mage from
					Heat treatment for 4 hours at 155°C
				flux	Solution of rosin ethanol 25 (mass) %
				Type of solder	Sn-3.0Ag-0.5Cu ( Lead Free Solder )
15			percent of the terminals should be welded y and evenly	welding temperature	245+/-5°C
					5+0/-0.5s
				Infiltration rate and reproduction rate	25+/-5mm/s
		Capacity	Within the specified tolerance	Test temperature	25°C
			Please refer to the specification sheet for a single particle		$\begin{array}{ c c c c c c }\hline material quality & Capacity & frequency & voltage \\ \hline Class I COG & C \leq 1000 pF & 1.0 \pm 0.1 MHz & 0.5 - 5.0 Vrms \\ \hline C>1000 pF & 1.0 \pm 0.1 KHz & 1.0 \pm 0.2 Vrms \\ \hline Class & X7R/ & C>10uF & 120 Hz \pm 24 Hz & 0.5 V \pm 0.1 Vrms \\ \hline I & X7S & C \leq 10 uF & 1.0 \pm 0.1 KHz & 1.0 \pm 0.2 Vrms \\ \hline \end{array}$
				Test temperature	25℃
	electrical character	T.D.	Please refer to the specification sheet for a	test voltage	rated voltage
	Electrical		single particle	charging interval Charging/dischar	Two minutes
	Characterization			ge current	Maximum 50mA
					Rated voltage (R.V.)test voltage $P_{V} \leq 100V$ 250% RV
					R.V.≤100V         250% KV           100V < R.V.≤200V
			Can withstand the test voltage without	Charging/dischar	$\frac{1000 \text{ (R.V.} 2000 \text{ (R.V.} 20$
		voltage	defects or abnormalities	ge current	R.V. > 500V 130% RV
					R.V.≥1000V 120% RV
				mathod of	Maximum 50mA
		surface	No defects or anomalies	erection	Weld the capacitor to the test substrate
		Capacitanc e changes	C0G: ±1% or ±0.5pF (whichever is greater) X7R/X7S : ±10%	lest method	The force is applied at a speed of 1mm/s to bend it, and the fixture radius is 340 mm
17	Flat board test	Q or D.F.	Same as initial specification value	The amplitude of bending	COG:3mm X7R/X7S:2mm
	Board Flex				60s
		I.R.	Same as the initial specification value		04.5 0201 0.3 0.9 0.3 0402 0.5 1.5 0.6 0603 0.6 2.2 0.9 0805 0.8 3.0 1.3 1206 2.0 4.4 1.7 1210 2.0 4.4 2.6
		surface	No defects or anomalies	method of erection	Weld the capacitor to the test substrate
		Capacitanc	Same as initial specification value		Apply a continuous force of 17.7N (1.8Kg)
18	Thrust test Terminal Strength	e changes	Same as initial specification value	acting force	*0402 Apply a force of 2N *0201 Apply a force of 1N
	-				Note: Apply force gradually to avoid impact
		I.R.	Same as the initial specification value	duration	on the measuring part 60+1s
				•	

No	item	Test specific	cations	Test method (Refe	erence	standa	ard: AEC-Q200-Rev E)	
				The pressure load	provid	les a s	speed of 0.1mm/s	
				Location diagram	: [Prod	uct L	size $\leq 2.5$ mm][Product L	_ size
		The		≥ 3.2mm]				
	Load testing Beam Load Test	value should exceed the	Product L size is less than 2.5mm Product T thickness> 0.5mm: 20N Product L size> = 3.2mm Product T thickness> = 1.25mm: 54N		1			
							Fig. d.	
		change in	The nominal value of the temperature coefficient is shown in the rated value. The change of capacitance at reference	each specified ten The capacitance v step value marked	nperatu alue is l with "	ure sta used '*".	as a reference value and is	the
			temperature is shown in Table A.	Capacitance	dividin	g the	f the change is calculated by difference between the nd minimum values	У
	Temperature			test voltage	Less th	an 1.0	0Vrms	
	characteristics				st	tep	temperature	
	Temperature Characteristics of					1	Reference temperature +/-2	
	Capacitance		C0G∶±30ppm/°C	Temperature step		2	Minimum operating temperature +/-3	
		e changes	X7R/X7S: ±15%	(A)	3	3*	Reference temperature +/-2	
						4	Maximum operating temperature +/-3	
						5	Reference temperature +/-2	

## product packaging

The tape reel packaging is the most common packaging method at present. A reel with a diameter of 180mm (7") can contain 1000~20000 capacitors, and can also be packaged according to customer requirements.

## 1. Tape size



	01005 ( 0402 )	0201 ( 0603 )	0402 (1005)	0603 (1608)	0805 ( 2012 )	1206 ( 3216 )
P1	2.00±0.05 ( 1.0±0.05 )				$4.00 \pm 0.10$	
P0		$4.00 \pm 0.10$			$4.00 \pm 0.10$	
P2		$2.00 \pm 0.05$		2.00±0.05		
А	$0.25 \pm 0.02$	0.38±0.03	$0.62 \pm 0.05$	$1.00 \pm 0.01$	$1.55 \pm 0.10$	2.05±0.10
В	$0.46 \pm 0.02$	0.68±0.03	1.12±0.05	1.90±0.10	2.30±0.10	3.60±0.10
W	8.00±0.30			8.00±0.30		
Е	$1.75 \pm 0.10$			1.75±0.10		
F	3.50±0.05			3.50±0.05		
D	φ1.50+0.10/-0.03			φ1.50+0.10/-0		
t	$0.25 \pm 0.02$	0.35±0.03	$0.60 \pm 0.05$	1.1Below		

2. Size of plastic bags



	0805 ( 2012 )	1206 ( 3216 )	1210 ( 3225 )	1808 ( 4520 )	1812 ( 4532 )	2220 ( 5750 )
P0	4.00±0.10	$4.00 \pm 0.10$	$4.00 \pm 0.10$	4.00±0.10	4.00±0.10	4.00±0.10
P1	$4.00 \pm 0.10$	$4.00 \pm 0.10$	$4.00 \pm 0.10$	$4.00 \pm 0.10$	8.00±0.10	8.00±0.10
P2	$2.00 \pm 0.05$	$2.00 \pm 0.05$	$2.00 \pm 0.05$	$2.00 \pm 0.05$	$2.00 \pm 0.05$	$2.00 \pm 0.05$
А	<1.80	<2.50	<3.20	<2.50	<3.90	<6.80
В	<2.70	<4.00	<4.00	<5.30	<5.30	<6.50
W	8.00±0.20	8.00±0.20	8.00±0.20	12.00±0.20	12.00±0.20	12.00±0.20
Е	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10	1.75±0.10
F	3.5±0.05	3.5±0.05/5.50± 0.05	3.5±0.05/5.50± 0.05	$5.50 \pm 0.05$	$5.50 \pm 0.05$	$5.50 \pm 0.05$
D	1.5 ( +0.1/-0.0 )	1.5 (+0.1/-0.0)	1.5 ( +0.1/-0.0 )	1.5 (+0.1/-0.0)	1.5 ( +0.1/-0.0 )	1.5 ( +0.1/-0.0 )
T1	2.5max.	2.5max.	3.5max.	2.5max.	3.0max.	3.1max.
T2	0.23±0.05	0.23±0.05/0.95± 0.05	0.23±0.05	0.30±0.1	0.30±0.1	0.30±0.1

3. Disk size



Disc size	A ( mm )	B ( mm )	C ( mm )	D ( mm )	E ( mm )	G ( mm )	T ( mm )
7"Reel	φ178±2.0	2.0±0.5	φ13±1.0	φ21±0.8	$\phi$ 50 or more	10±1.0	13±1.0

## 4. Instructions for use of roll tape

When the finished product is used, the upper belt (membrane) is peeled at a speed of  $300 \pm 10$  mm/min and an Angle of  $165^{\circ} \sim 180^{\circ}$  (as shown in the figure below), with a peel strength of  $0.1N \sim 0.7N(10g.f \le peel force \le 70g.f)$ .





### 5. Welded plate size

Please confirm the appropriate size by evaluating the actual SET/PCB.



#### wave-soldering

Size (U	nit: mm)	a	b	с
0603	1.60*0.80mm	0.6~1.0	0.8~0.9	0.6~0.8
0805	2.00*1.25mm	1.0~1.2	0.9~1.0	0.8~1.1
1206	3.20*1.60mm	2.2~2.6	1.0~1.1	1.0~1.4

reflow soldering

tenow soluting						
Size (Unit: mm)		а	b	с		
0201	0.60*0.30mm	0.2~0.3	0.2~0.35	0.25~0.4		
0402	1.00*0.50mm	0.3~0.6	0.35~0.5	0.4~0.7		
0603	1.60*0.80mm	0.6~0.9	0.6~0.8	0.6~1.0		
0805	2.00*1.25mm	1.0~1.4	0.6~0.8	1.2~1.4		
1206	3.20*1.60mm	1.8~2.1	1.9~1.3	1.5~1.9		
1210	3.20*2.50mm	2.0~2.4	1.0~1.2	1.8~2.3		

### **Use precautions**

Multilayer ceramic chip capacitors (MLCCs) may experience short circuits, open circuits, or even smoke, burn, or explode under harsh working conditions exceeding the usage frequency specified in this acceptance document or related manuals, or when subjected to excessive external mechanical forces. Therefore, when using them, please first refer to the relevant instructions in this acceptance document. If you have any questions, please contact our Technical Department, Quality Control Department, or Production Department.

- 1. The amount of solder used in welding
- A. Too much solder can cause damage to the capacitor due to excessive pressure at the end of the capacitor.



B. Too little solder and insufficient fixing force may cause poor contact between the capacitor chip and the line.



- 2. Recommended solder usage:
- A. Optimal solder quantity for reflow welding



B. Optimal solder usage for peak welding



C. The best amount of solder to use when using a soldering iron for repair



#### 3. Precautions for printing PCB board

After the MLCC is installed on the PCB, do not apply any stress to the MLCC, such as bending or twisting the board.

- $\cdot$  Stress as shown in the figure may cause cracks in MLCC when cutting the board.
- · MLCC cracking may lead to a decrease in insulation resistance, resulting in a short circuit.
- · Avoid applying these types of stress to MLCC.



#### 3.1 Precautions for cutting PCB board

Check the PCB cutting method in advance.

The high density board is divided into many separate boards after welding. If the board bends or deforms during separation, the MLCC may break.

Carefully select a separation method to minimize PCB deformation

3.2 Product layout and chip PCB

When breaking a PCB, the layout should pay attention to mechanical stress depending on the position of the capacitor. The following example shows suggestions for better design.



#### 3.3 An example of a disk separator

The contour of the disc separator is shown below. As shown in the working principle, the upper and lower blades align with the  $\nu$ -shaped groove on the printed circuit board to separate it. In the following cases, bending stress will be applied to the board surface and cause cracks in the capacitor.

(1) The upper and lower blades are misaligned, such as the upper and lower, left and right, front and back directions

(2) The Angle of the V-shaped groove is too low, the depth of the V-shaped groove is too shallow, or the V-shaped groove is misaligned

If the V slot is too deep, it may brake during handling. Take into account the strength of the PCB material and carefully design the depth of the V slot.



### 4. Recommended welding temperature curve:

Welding mode	≤0402	0603	0805	1206	≥1210
reflow soldering	All specifications	>1.0µF	>2.2µF	>4.7µF	All specifications
Return/wave soldering		≤1.0µF	≤2.2µF	≤4.7µF	



Type of solder	Pb-Sn weld	lead-free soldering
Peak temperatures	230°C~250°C	240°C~260°C
Peak time	3s~10s	3s~10s

#### Boltzman distribution law



Type of solder	Pb-Sn weld	lead-free soldering	
Peak temperatures	230°C~260°C	240°C~270℃	
Peak time	Within 3 seconds	Within 3 seconds	

manual welding

Manual welding is easy to cause micro-cracking or local bursting of porcelain body because of uneven heating of the capacitor. Therefore, when using soldering iron for manual welding, it should be carefully operated, and more care should be taken in the selection of the tip of the soldering iron and the control of the tip temperature.



preheat	The temperature of the soldering iron	Wattage of the soldering iron	Diameter of the soldering iron head	weld period	The amount of ointment	matters need attention
≙≤ 130°C	≤350°C	≤20W	Suggest 1mm	≤3s	Less than 1/2 capacitance height	Do not touch the ceramic body directly with the iron head